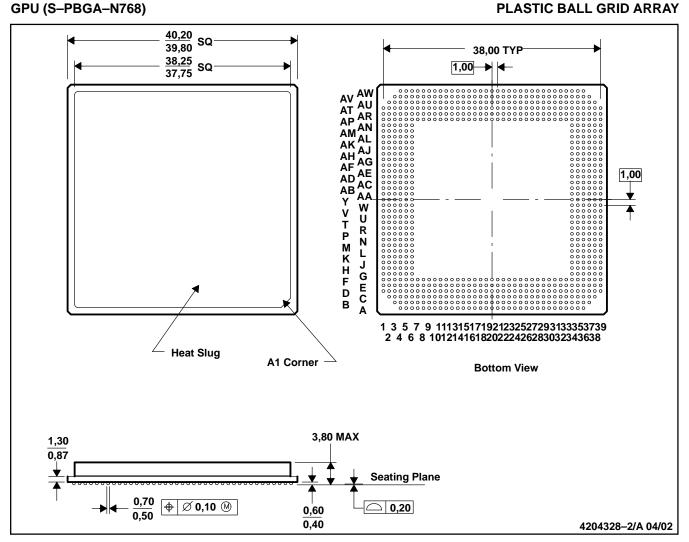
MECHANICAL DATA

MPBG249 - APRIL 2002

PLASTIC BALL GRID ARRAY



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Flip chip application only.



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